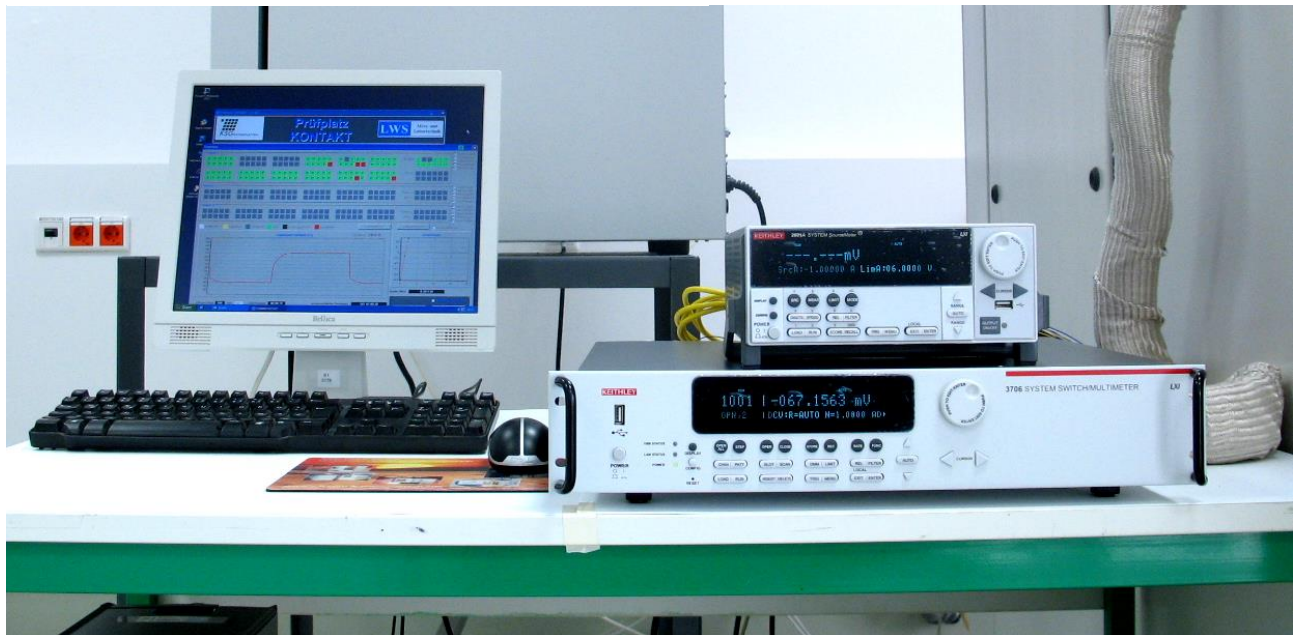


Test System for Characterizing the DC-Impedance of Electrical Structures on Printed-Circuit-Boards

A test system for characterizing the long-time behavior of the DC-impedance of electrical structures on printed-circuit-boards exposed to thermal stress has been developed. The devices under test - i.e. electrical structures on PCBs like vias – are submitted to continuous thermal cycles while their DC-impedance is measured via high-precision four-wire sensing. Resistance changes as small as 3% and 1% for vias can reliably be detected. Thus, making the system indispensable in characterizing new PCB materials and fabrication techniques. Special emphasis has been placed on easy system handling and operation.

Control computer and Measurement Equipment used



Climatic Chamber



Technical Parameter:

- 24 slots for 10 vias each
- PCBs of different thickness can be characterized in parallel
- possible grouping of vias with identical parameter, e.g. same diameter
- possibility to remove PCBs from individual slots without interfering with other slots
- adjustment of all process parameters possible, a special measurement program according to VdL/ZVEI feasible
- easy handling of the entire Test System
 - short process times by incorporating of plug-in connectors instead of soldering
 - well-arranged Human-Machine-Interface (HMI)
 - clear visualization of the actual process flow and all relevant intermediate and final results
- safe storage of all important process parameter and measurement values

**Special-Purpose Solutions are our daily business.
So, LWS is capable to adapt the system according to special customer requirements.**

Human-Machine-Interface:

Windows-HMI for System Control



